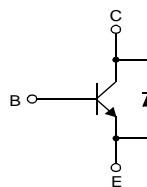


KSC5502D/KSC5502DT

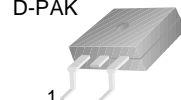
High Voltage Power Switch Switching Application

- Wide Safe Operating Area
- Built-in Free-Wheeling Diode
- Suitable for Electronic Ballast Application
- Small Variance in Storage Time
- Two Package Choices : D-PAK or TO-220

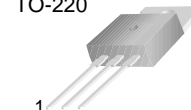
Equivalent Circuit



D-PAK



TO-220



1.Base 2.Collector 3.Emitter

NPN Triple Diffused Planar Silicon Transistor

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage	1200	V
V_{CEO}	Collector-Emitter Voltage	600	V
V_{EBO}	Emitter-Base Voltage	12	V
I_C	Collector Current (DC)	2	A
I_{CP}	*Collector Current (Pulse)	4	A
I_B	Base Current (DC)	1	A
I_{BP}	*Base Current (Pulse)	2	A
P_C	Collector Dissipation ($T_C=25^\circ\text{C}$)	50	W
T_J	Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature	- 65 ~ 150	$^\circ\text{C}$
EAS	Avalanche Energy($T_J=25^\circ\text{C}$)	2.5	mJ

* Pulse Test : Pulse Width = 5ms, Duty Cycle \leq 10%

Thermal Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Characteristics		Rating	Unit
$R_{\theta jc}$	Thermal Resistance	Junction to Case	2.5	$^\circ\text{C/W}$
$R_{\theta ja}$		Junction to Ambient	62.5	
T_L	Maximun Lead Temperature for Soldering Purpose : 1/8" from Case for 5 seconds		270	$^\circ\text{C}$

Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units	
BV_{CBO}	Collector-Base Breakdown Voltage	$I_C=1\text{mA}, I_E=0$	1200	1350		V	
BV_{CEO}	Collector-Emitter Breakdown Voltage	$I_C=5\text{mA}, I_B=0$	600	750		V	
BV_{EBO}	Emitter-Base Breakdown Voltage	$I_E=500\mu\text{A}, I_C=0$	12	13.7		V	
I_{CES}	Collector Cut-off Current	$V_{CES}=1200\text{V}, V_{BE}=0$	$T_C=25^\circ\text{C}$		100	μA	
			$T_C=125^\circ\text{C}$		500		
I_{CEO}	Collector Cut-off Current	$V_{CE}=600\text{V}, I_B=0$	$T_C=25^\circ\text{C}$		100	μA	
			$T_C=125^\circ\text{C}$		500		
I_{EBO}	Emitter Cut-off Current	$V_{EB}=12\text{V}, I_C=0$			10	μA	
h_{FE}	DC Current Gain	$V_{CE}=1\text{V}, I_C=0.2\text{A}$	$T_C=25^\circ\text{C}$	15	28	40	
			$T_C=125^\circ\text{C}$	8	18		
		$V_{CE}=1\text{V}, I_C=1\text{A}$	$T_C=25^\circ\text{C}$	4	6.4		
			$T_C=125^\circ\text{C}$	3	4.7		
		$V_{CE}=2.5\text{V}, I_C=0.5\text{A}$	$T_C=25^\circ\text{C}$	12	20	30	
			$T_C=125^\circ\text{C}$	6	12		
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=0.2\text{A}, I_B=0.02\text{A}$	$T_C=25^\circ\text{C}$		0.31	0.8	V
			$T_C=125^\circ\text{C}$		0.54	1.1	V
		$I_C=0.4\text{A}, I_B=0.08\text{A}$	$T_C=25^\circ\text{C}$		0.15	0.6	V
			$T_C=125^\circ\text{C}$		0.23	1.0	V
		$I_C=1\text{A}, I_B=0.2\text{A}$	$T_C=25^\circ\text{C}$		0.40	1.5	V
			$T_C=125^\circ\text{C}$		1.3	3.0	V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C=0.4\text{A}, I_B=0.08\text{A}$	$T_C=25^\circ\text{C}$		0.77	1.0	V
			$T_C=125^\circ\text{C}$		0.60	0.9	V
		$I_C=1\text{A}, I_B=0.2\text{A}$	$T_C=25^\circ\text{C}$		0.83	1.2	V
			$T_C=125^\circ\text{C}$		0.70	1.0	V
C_{ib}	Input Capacitance	$V_{EB}=8\text{V}, I_C=0, f=1\text{MHz}$		385	500	pF	
C_{ob}	Output Capacitance	$V_{CB}=10\text{V}, I_E=0, f=1\text{MHz}$		60	100	pF	
f_T	Current Gain Bandwidth Product	$I_C=0.5\text{A}, V_{CE}=10\text{V}$		11		MHz	
V_F	Diode Forward Voltage	$I_F=0.2\text{A}$	$T_C=25^\circ\text{C}$		0.75	1.2	V
			$T_C=125^\circ\text{C}$		0.59		V
		$I_F=0.4\text{A}$	$T_C=25^\circ\text{C}$		0.80	1.3	V
			$T_C=125^\circ\text{C}$		0.64		V
		$I_F=1\text{A}$	$T_C=25^\circ\text{C}$		0.9	1.5	V

Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Min	Typ.	Max.	Units	
t_{fr}	Diode Forward Recovery Time ($di/dt=10\text{A}/\mu\text{s}$)	$I_F=0.2\text{A}$		650		ns	
		$I_F=0.4\text{A}$		740		ns	
		$I_F=1\text{A}$		785		ns	
$V_{CE(DSAT)}$	Dynamic Saturation Voltage	$I_C=0.4\text{A}, I_{B1}=80\text{mA}$ $V_{CC}=300\text{V}$	@ $1\mu\text{s}$	7.2		V	
			@ $3\mu\text{s}$	1.8		V	
		$I_C=1\text{A}, I_{B1}=200\text{mA}$ $V_{CC}=300\text{V}$	@ $1\mu\text{s}$	18		V	
			@ $3\mu\text{s}$	6		V	
RESISTIVE LOAD SWITCHING (D.C $\leq 10\%$, Pulse Width=20s)							
t_{ON}	Turn On Time	$I_C=0.4\text{A},$ $I_{B1}=80\text{mA}$	$T_C=25^\circ\text{C}$		175	350	ns
			$T_C=125^\circ\text{C}$		185		ns
t_{OFF}	Turn Off Time	$I_{B2}=0.2\text{A},$ $V_{CC}=300\text{V}$ $R_L = 750\Omega$	$T_C=25^\circ\text{C}$		2.1	3.0	μs
			$T_C=125^\circ\text{C}$		2.6		μs
t_{ON}	Turn On Time	$I_C=1\text{A},$ $I_{B1}=160\text{mA}$	$T_C=25^\circ\text{C}$		240	450	ns
			$T_C=125^\circ\text{C}$		310		ns
t_{OFF}	Turn Off Time	$I_{B2}=160\text{mA},$ $V_{CC}=300\text{V}$ $R_L = 300\Omega$	$T_C=25^\circ\text{C}$		3.7	5.0	μs
			$T_C=125^\circ\text{C}$		4.5		μs
INDUCTIVE LOAD SWITCHING ($V_{CC}=15\text{V}$)							
t_{STG}	Storage Time	$I_C=0.4\text{A},$ $I_{B1}=80\text{mA}$	$T_C=25^\circ\text{C}$		1.2	2.0	μs
			$T_C=125^\circ\text{C}$		1.5		μs
t_F	Fall Time	$I_{B2}=0.2\text{A},$ $V_Z=300\text{V}$ $L_C=200\text{H}$	$T_C=25^\circ\text{C}$		90	200	ns
			$T_C=125^\circ\text{C}$		65		ns
t_C	Cross-over Time		$T_C=25^\circ\text{C}$		185	350	ns
			$T_C=125^\circ\text{C}$		145		ns
t_{STG}	Storage Time	$I_C=0.8\text{A},$ $I_{B1}=160\text{mA}$	$T_C=25^\circ\text{C}$		3.3	4.5	μs
			$T_C=125^\circ\text{C}$		3.75		μs
t_F	Fall Time	$I_{B2}=160\text{mA},$ $V_{CC}=300\text{V}$ $L_C=200\text{H}$	$T_C=25^\circ\text{C}$		90	250	ns
			$T_C=125^\circ\text{C}$		160		ns
t_C	Cross-over Time		$T_C=25^\circ\text{C}$		300	600	ns
			$T_C=125^\circ\text{C}$		570		ns

Typical Characteristics

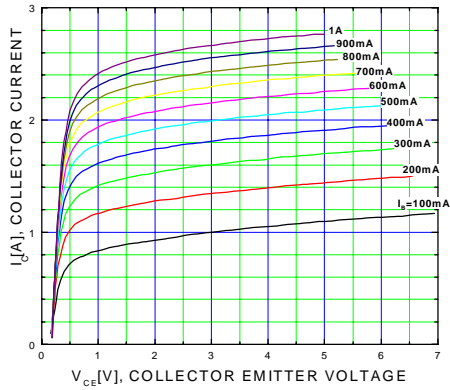


Figure 1. Static Characteristic

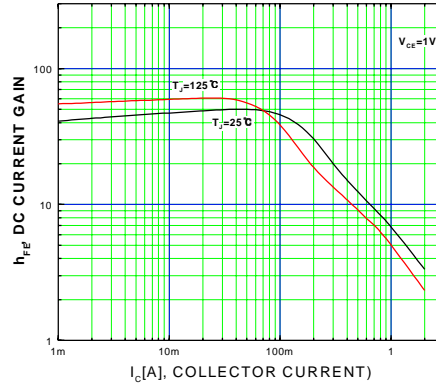


Figure 2. DC current Gain

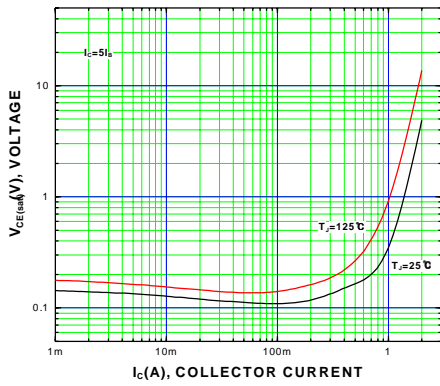


Figure 3. Collector-Emitter Saturation Voltage

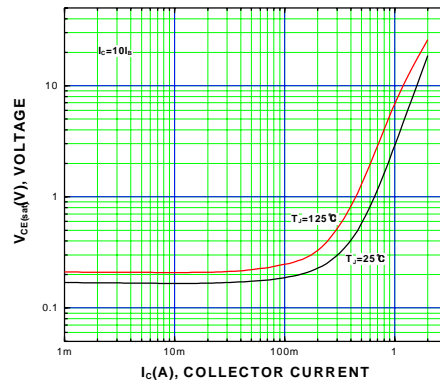


Figure 4. Collector-Emitter Saturation Voltage

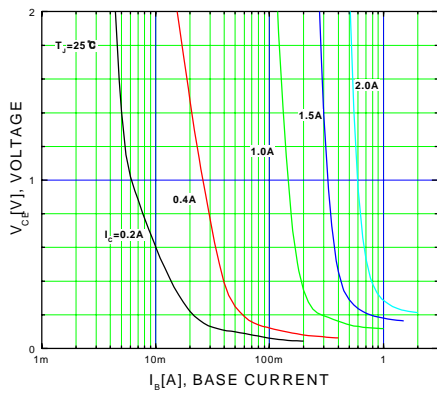


Figure 5. Typical Collector Saturation Voltage

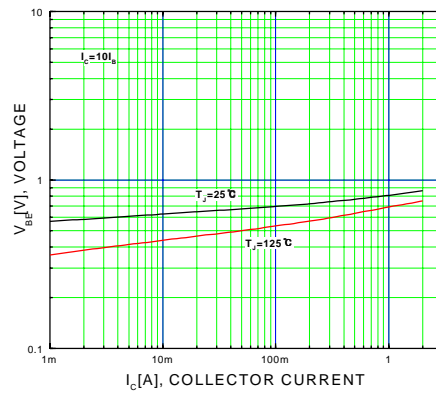


Figure 6. Base-Emitter Saturation Voltage

Typical Characteristics (Continued)

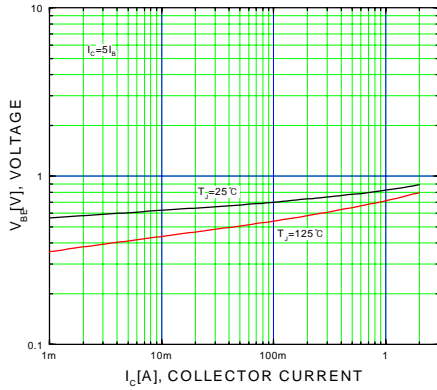


Figure 7. Base-Emitter Saturation Voltage

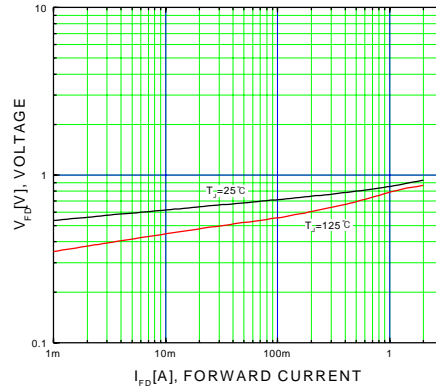


Figure 8. Diode Forward Voltage

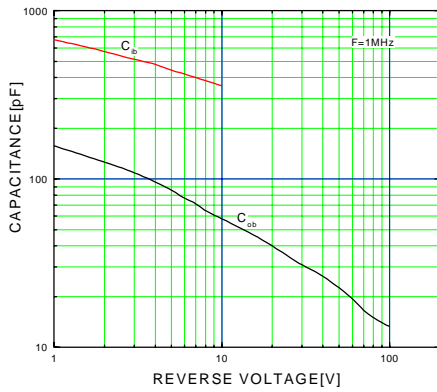


Figure 9. Collector Output Capacitance

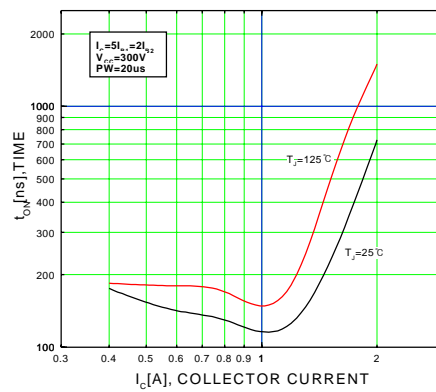


Figure 10. Resistive Switching Time, t_{on}

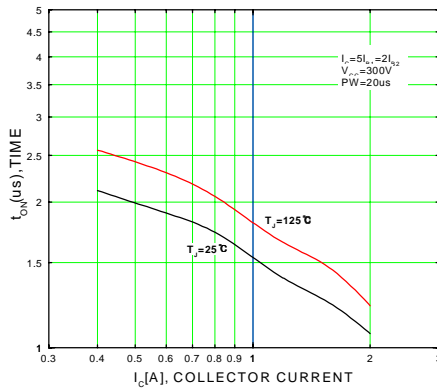


Figure 11. Resistive Switching Time, t_{off}

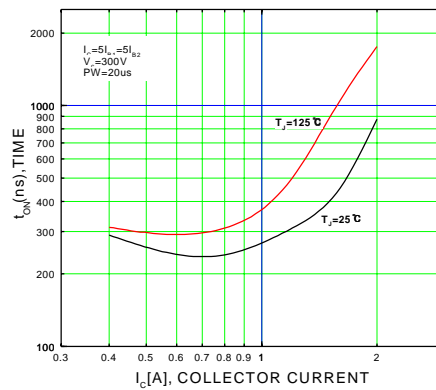


Figure 12. Resistive Switching Time, t_{on}

Typical Characteristics (Continued)

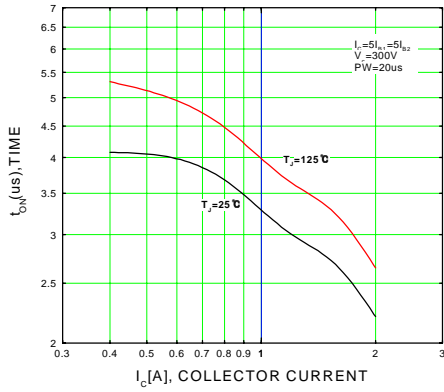


Figure 13. Resistive Switching Time, t_{on}

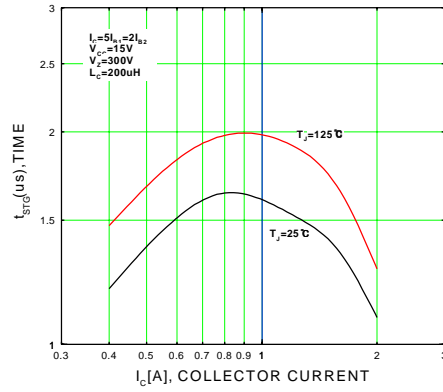


Figure 14. Inductive Switching Time, t_{STG}

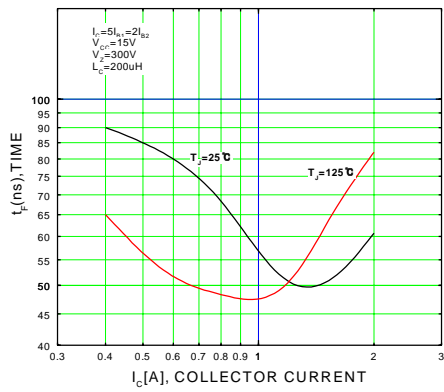


Figure 15. Inductive Switching Time, t_f

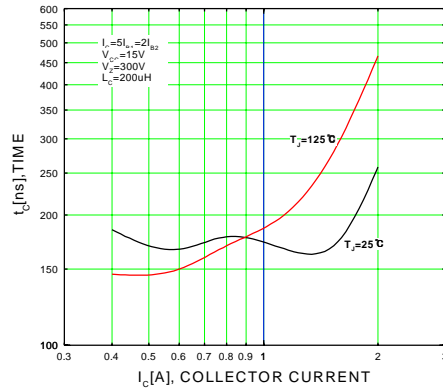


Figure 16. Inductive Switching Time, t_c

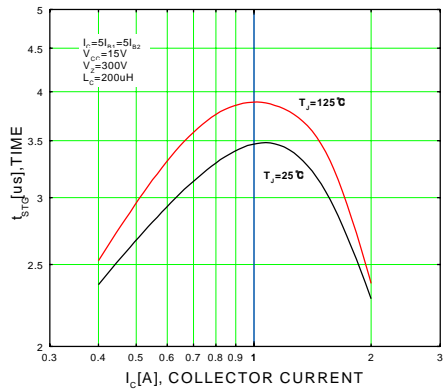


Figure 17. Inductive Switching Time, t_{STG}

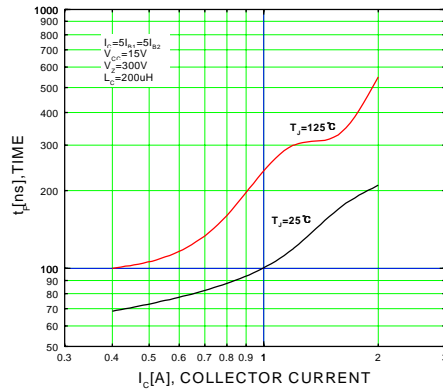


Figure 18. Inductive Switching Time, t_f

Typical Characteristics (Continued)

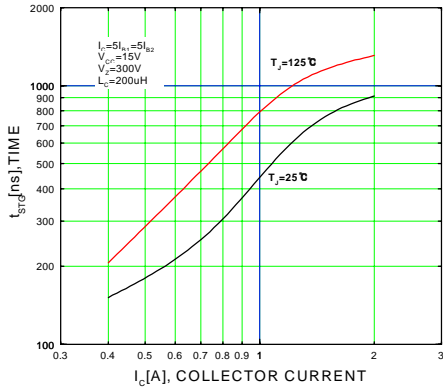


Figure 19. Inductive Switching Time, t_c

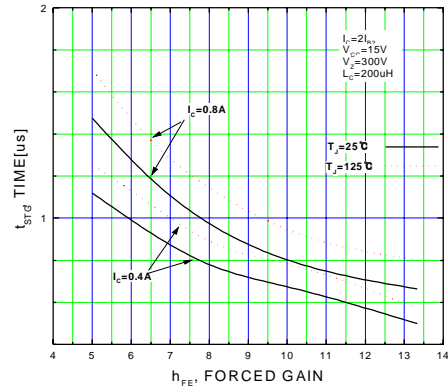


Figure 20. Inductive Switching Time, t_{STG}

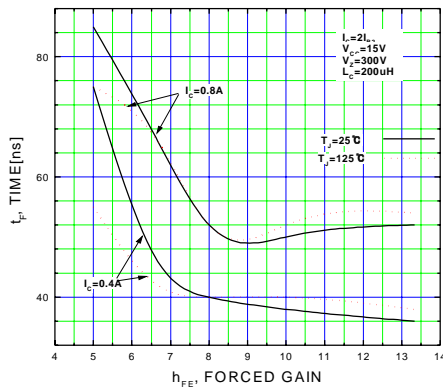


Figure 21. Inductive Switching Time, t_r

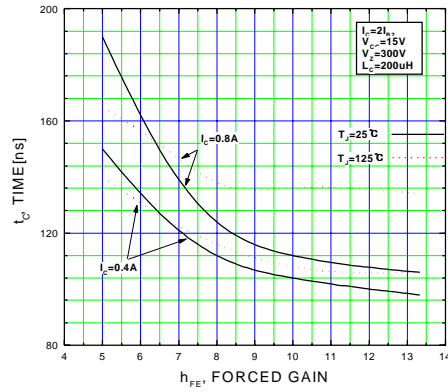


Figure 22. Inductive Switching Time, t_c

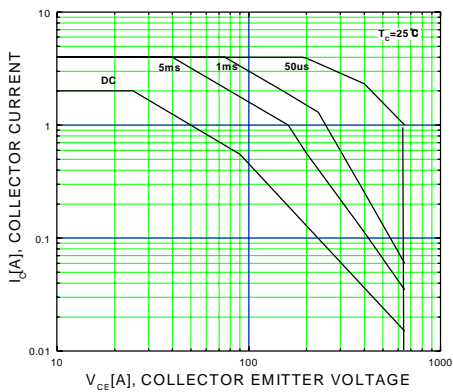


Figure 23. Forward Bias Safe Operating Area

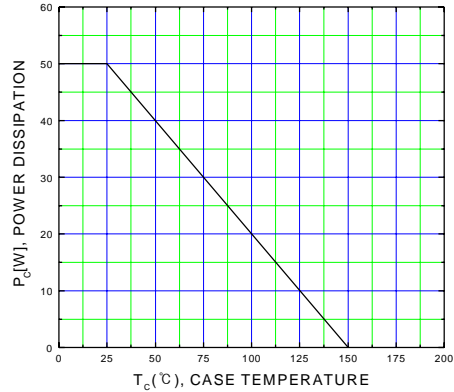


Figure 24. Power Derating

Typical Characteristics (Continued)

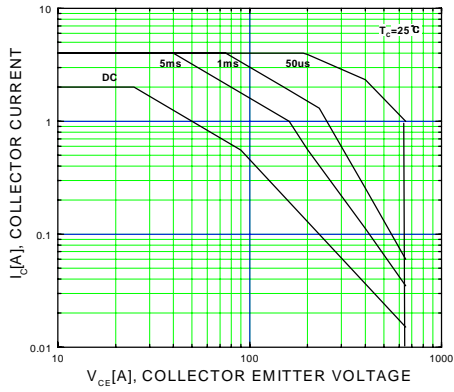


Figure 25. Forward Bias Safe Operating Area

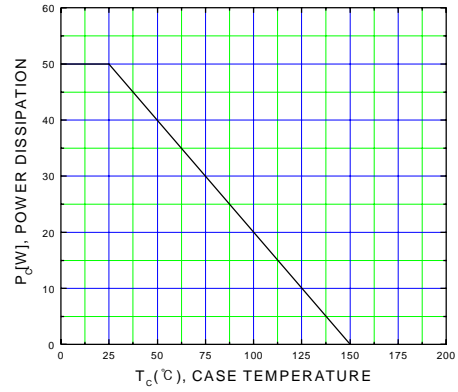
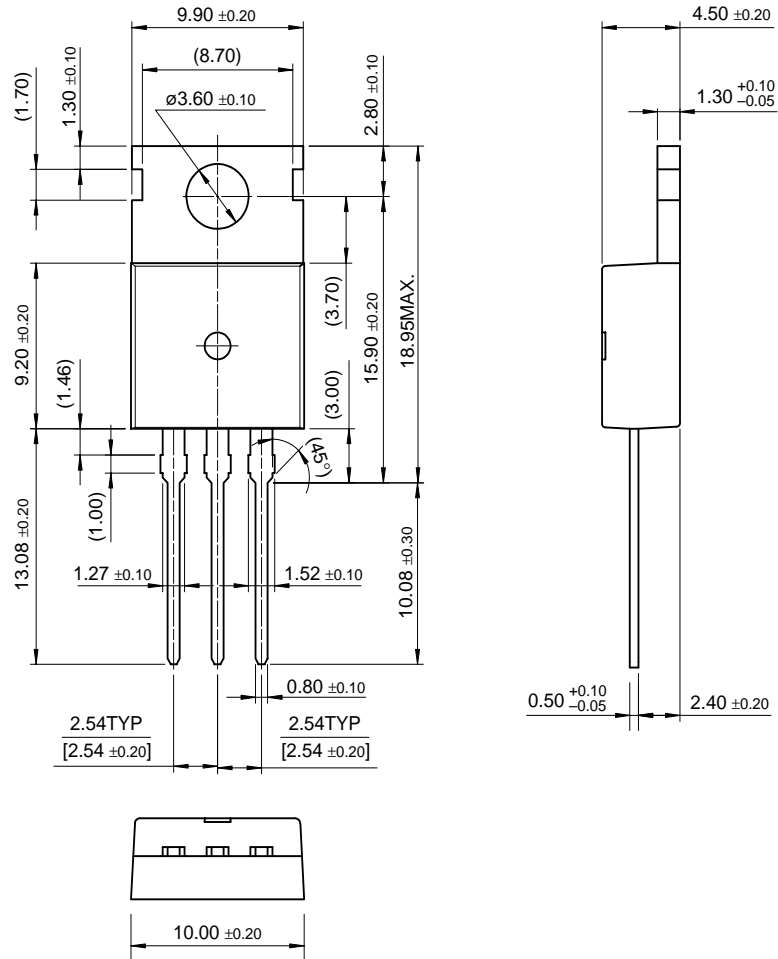


Figure 26. Power Derating

Package Dimensions

TO-220



KSC5502D/KSC5502DT

Dimensions in Millimeters

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PRODUCT STATUS DEFINITIONS

Definition of Terms

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